ANALOG DEVICES

Qualification Results Summary for
Multi Die in LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION RESULTS			
Test	Specification	Sample Size	Result
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**3 x 77**	**PASS**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 77**	**PASS**
Autoclave (AC)*	JEDEC *JESD22-A102*	**3 x 77**	**PASS**
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**3 x 11**	**PASS**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1 x 77**	**PASS**
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	**3/Voltage**	**PASS ±750V**

*Preconditioned per JEDEC/IPC J-STD-020